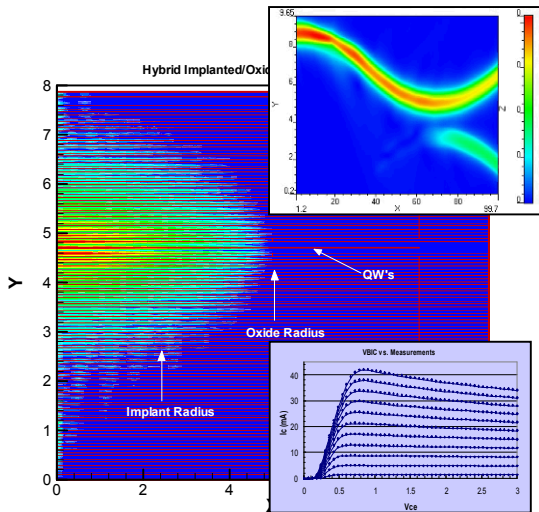


III-V Photonics at Sandia

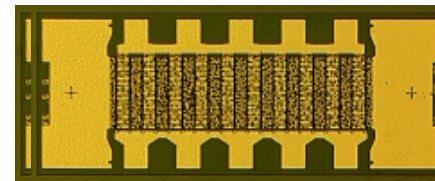
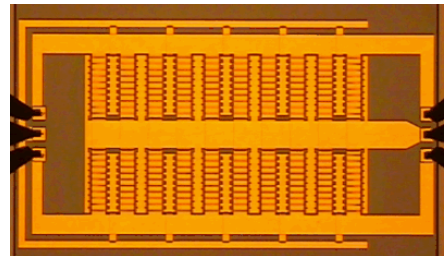
SAND2013-7505P

Allen Vawter, gavawte@sandia.gov, 505/844-9004

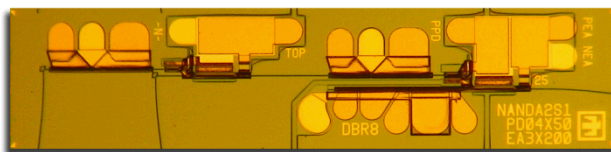
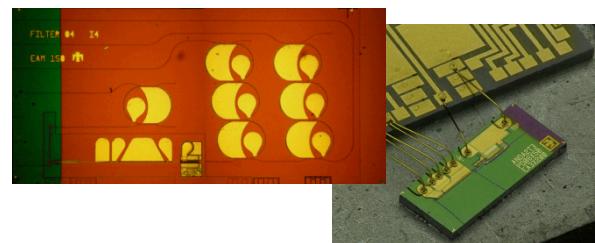
- Foundational Capabilities
 - III-V compound semiconductor epitaxy, microfabrication, integration
 - Device physics, modeling, simulation
 - Microelectronics/optoelectronics, and complex mono/hetero-circuits
- Prove, Advance Technology Readiness Level, Productize
 - TRL1-6+: create, develop, prototype
 - NNSA QMS/QC-1-10; trusted
- Trusted, custom, low-volume, high-reliability products for harsh environments when industry is unwilling or unable to deliver



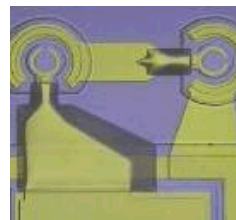
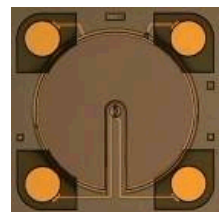
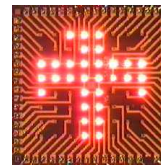
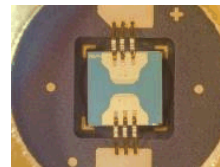
Modeling and Simulation



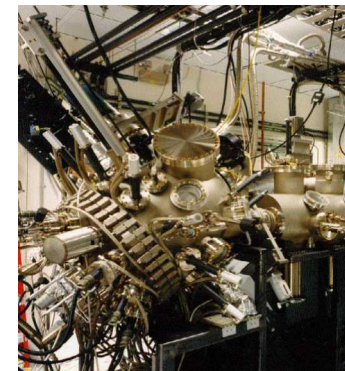
Compound Semiconductor Microelectronics



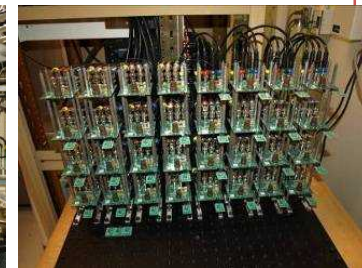
Photonic Integrated Circuits



VCSELs/RCPDs/EAMs/PCSS



Epitaxy



TRL 6 Lifetest

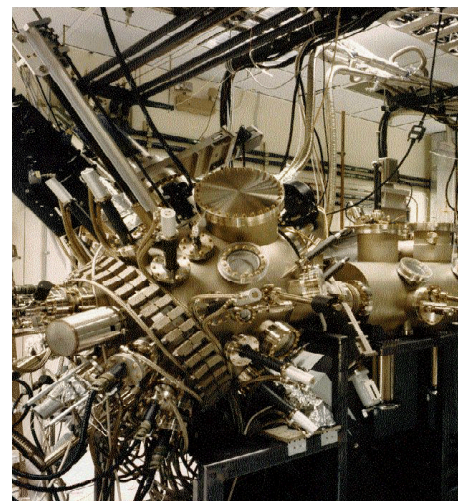
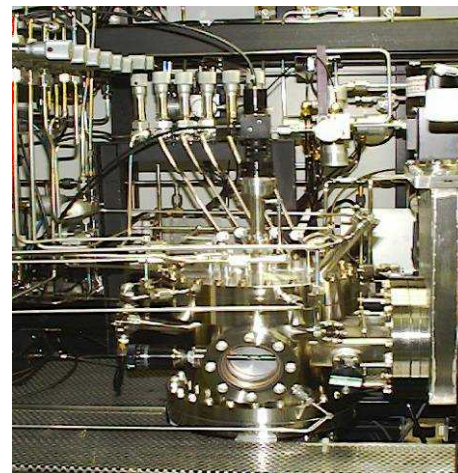
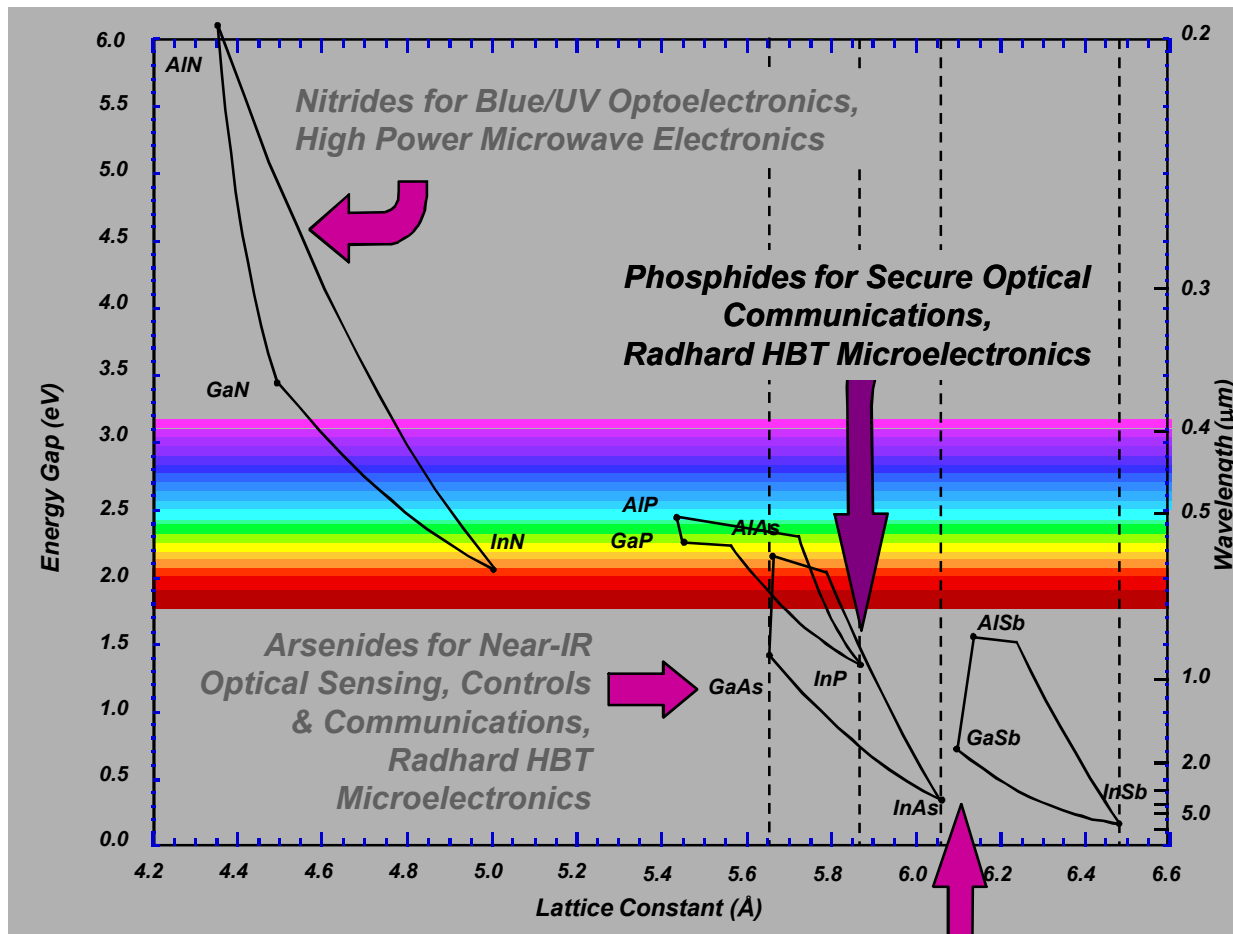
Group III-V Semiconductor Photonics at Sandia

Sandia Grows the Full Spectrum of III-V Materials

6 – MOCVD: As, P, Sb, N

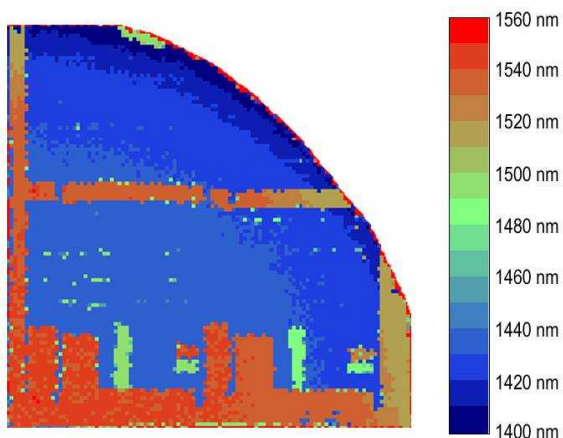
4 – MBE: As, P, Sb

3 – research tools

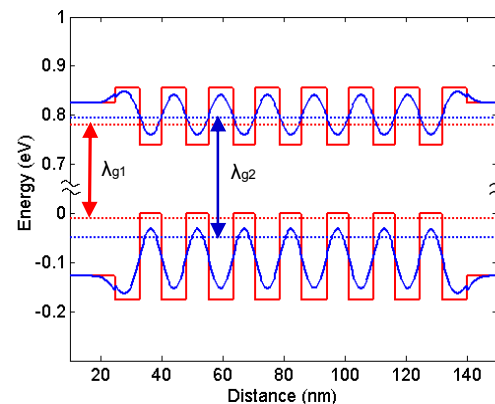
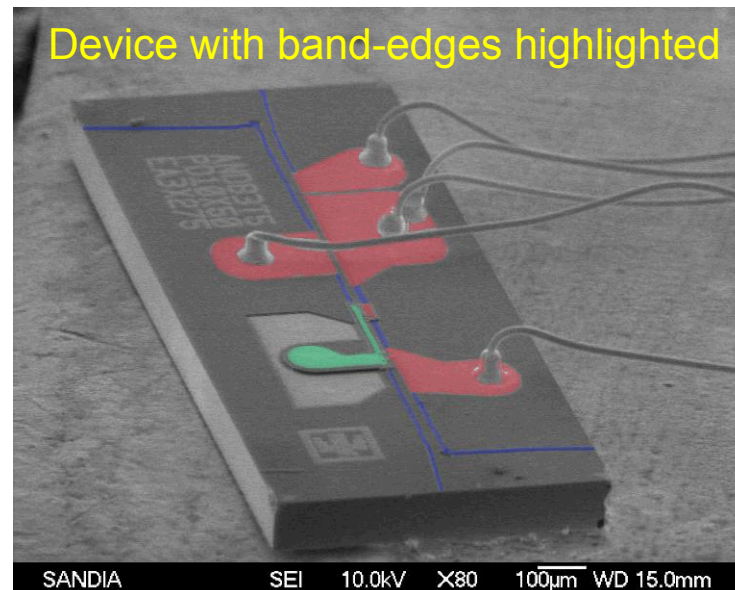
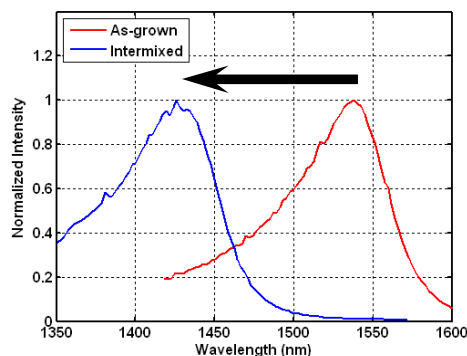


Post-Growth Bandgap Engineering

- Integrate devices with different functionalities
 - Ability to **program QW band edge -> shift from absorbing to transmitting**
- Artificially introduced defects reduce the activation energy for migration of atoms on lattice sites



PL map of intermixed quarter wafer

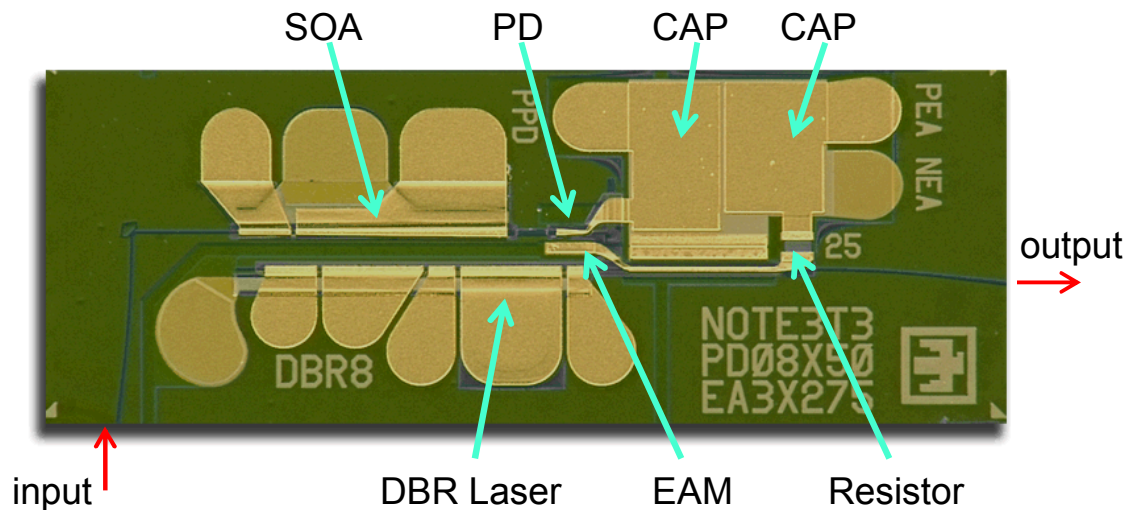


- Photoluminescence
 - Active = 1540nm, Passive = 1425nm

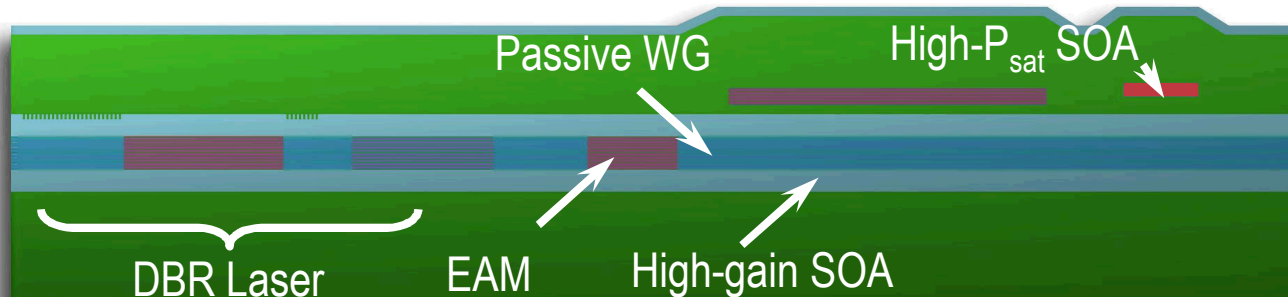
InP PICs for Multi- λ , High-Performance Optical Circuits

– InGaAsP/InP

- 1550 nm wavelength
- State-of-the-art discrete photonic component performance from a single chip
 - Light generation, modulation, amplification, routing, switching and detection
- 40Gb/s optical transceivers
- WDM systems for avionics networks

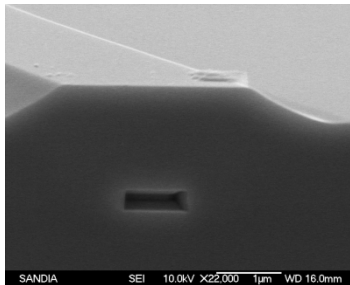
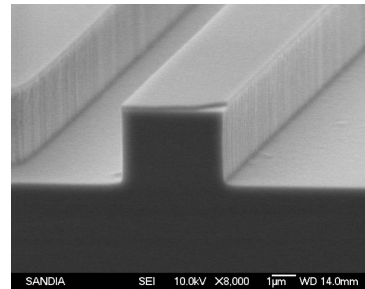
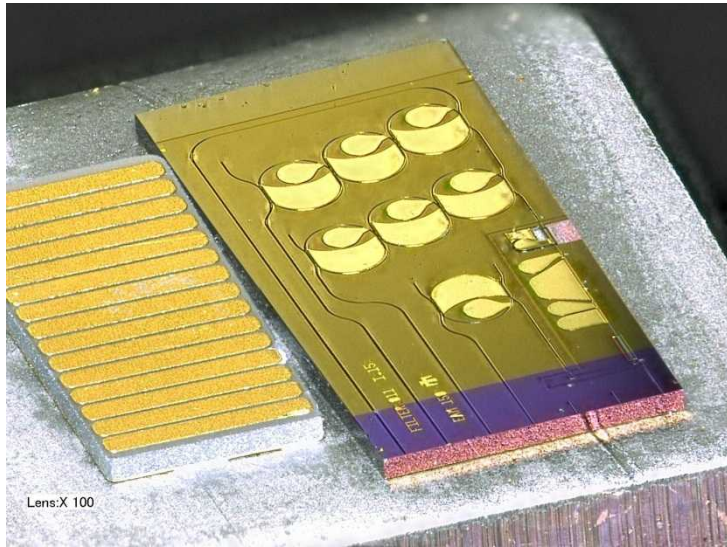


- Complete integration toolbox
- Diverse set of devices
 - DBR lasers, EAMs, WGs, High-gain SOAs, High- P_{sat} SOAs, Evanescent PD
- Low internal interconnect losses
- Low reflections and optical feedback



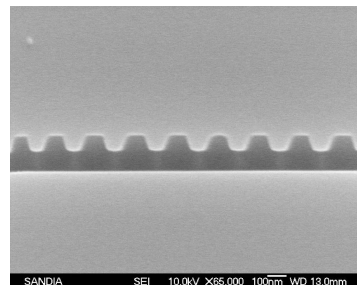
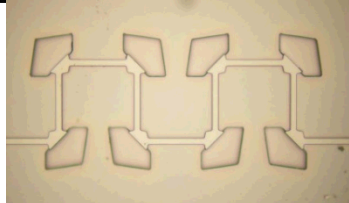
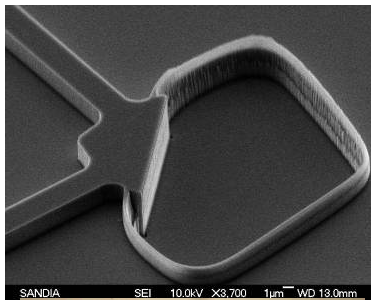
SNL Photonic Integrated Circuits

- State of the art – InP Photonic Integrated Circuits

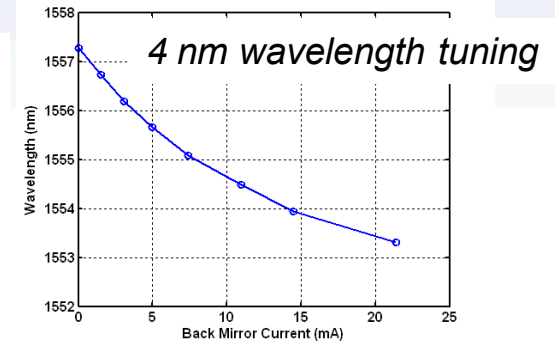
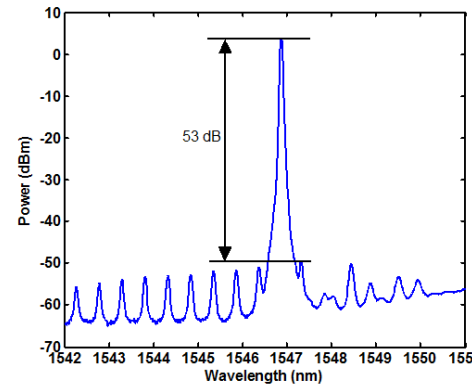
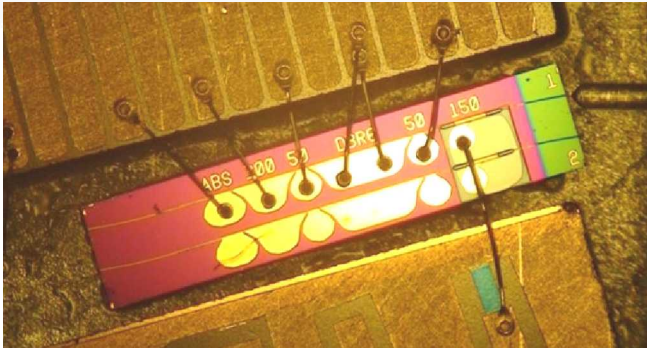


of unique components

Infinera	UCSB	Sandia
6	8	10
Waveguides	Waveguides	Waveguides
Laser	Laser	Laser
SOA	SOA	SOA High Gain
EAM	Delay Line	SOA High P_{sat}
Power Monitor	Phase Shifter	Power Monitor
AWG	Optical Atten.	EAM
	MMI	Photodiode
	AWG	TIR Mirror
		Resistor
		Capacitor



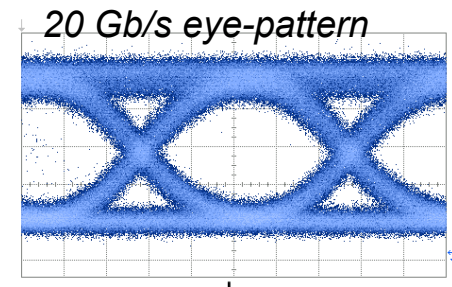
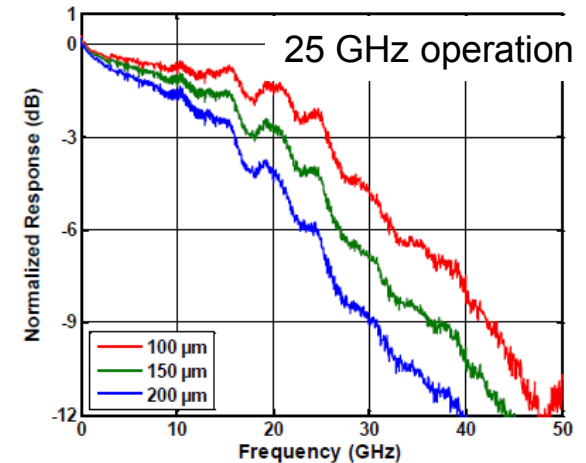
High-Speed Electrical-to-Optical (EO) Transmitter



- InGaAsP Diode laser and modulator chip
 - DBR lasers
 - 6 mW fiber-coupled power
 - ~20 mW out from chip
 - 4 nm wavelength tuning
 - EAMs
 - Efficiency ~19dB/V DC
 - Bandwidth 20GHz
- Wavelength tuning
 - Track filter frequencies
 - Tune to WDM channels

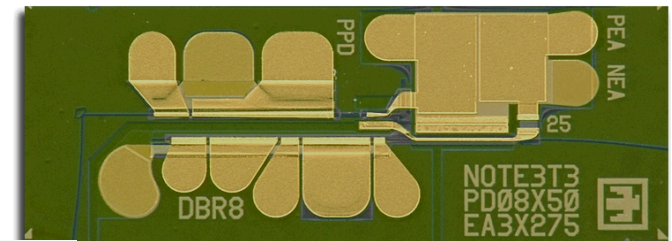
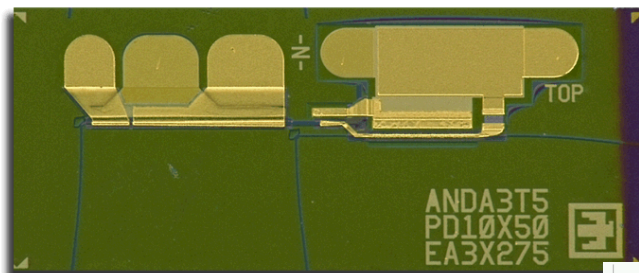
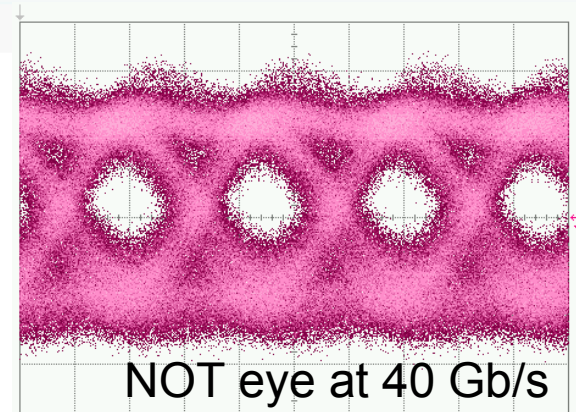
Power for RF photonics
Wavelength agility

Scalable to mm-wave

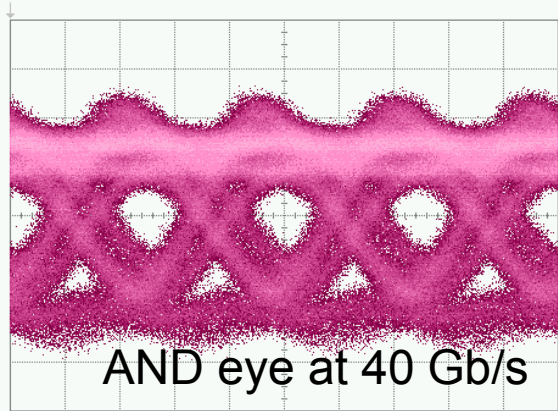
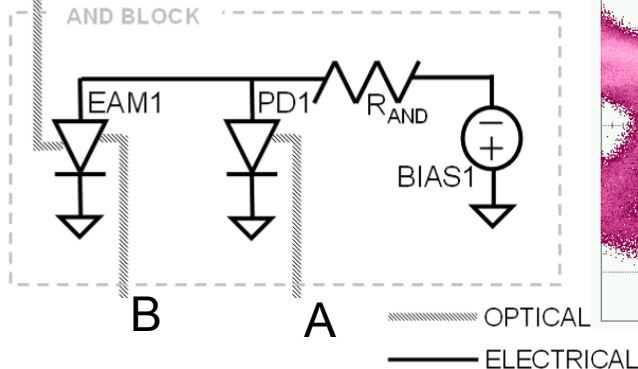


Sandia InGaAsP/InP All-Optical Logic Chips

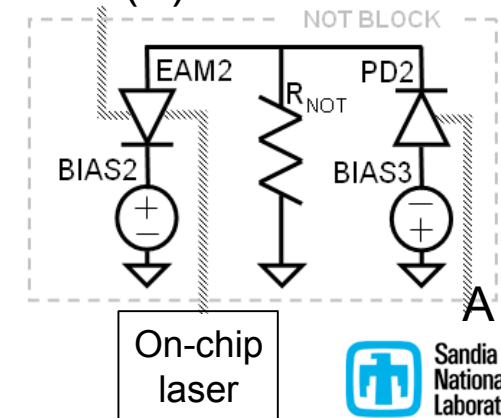
- EAMs, PDs, DFB lasers, etc. integrated to form all-optical logic gates
 - AND, NOT gates operating at 40 Gb/s
 - PDs detect input light and drive EAMs to modulate output
- Presented at Photonics in Switching 2010 conf.
 - Skogen, Vawter, Tauke-Pedretti, „Optical Logic Gates Using Interconnected Photodiodes and Electro-Absorption Modulators”



A AND B

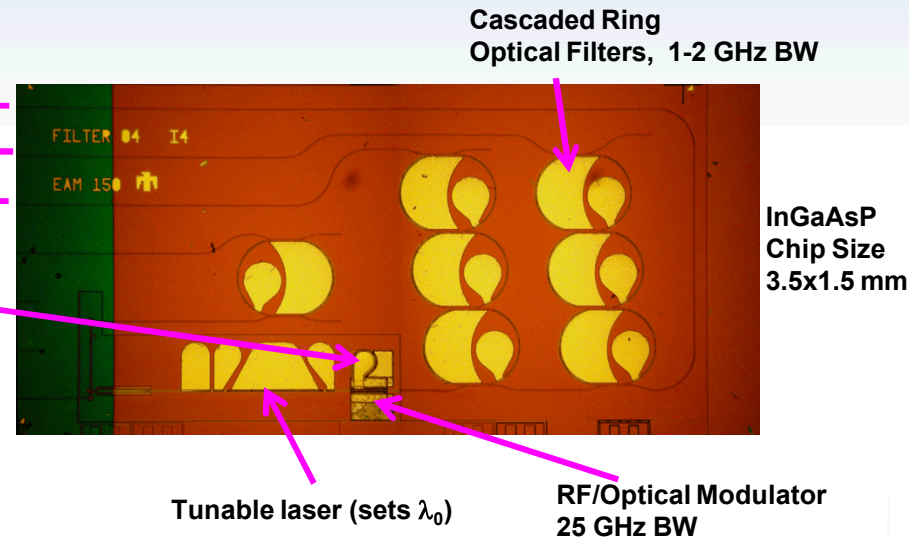
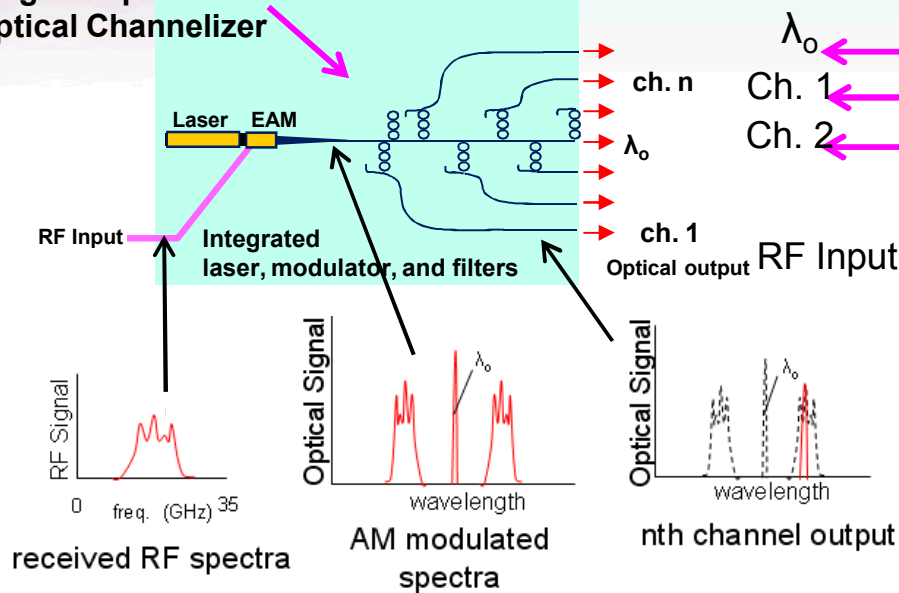


NOT(A)



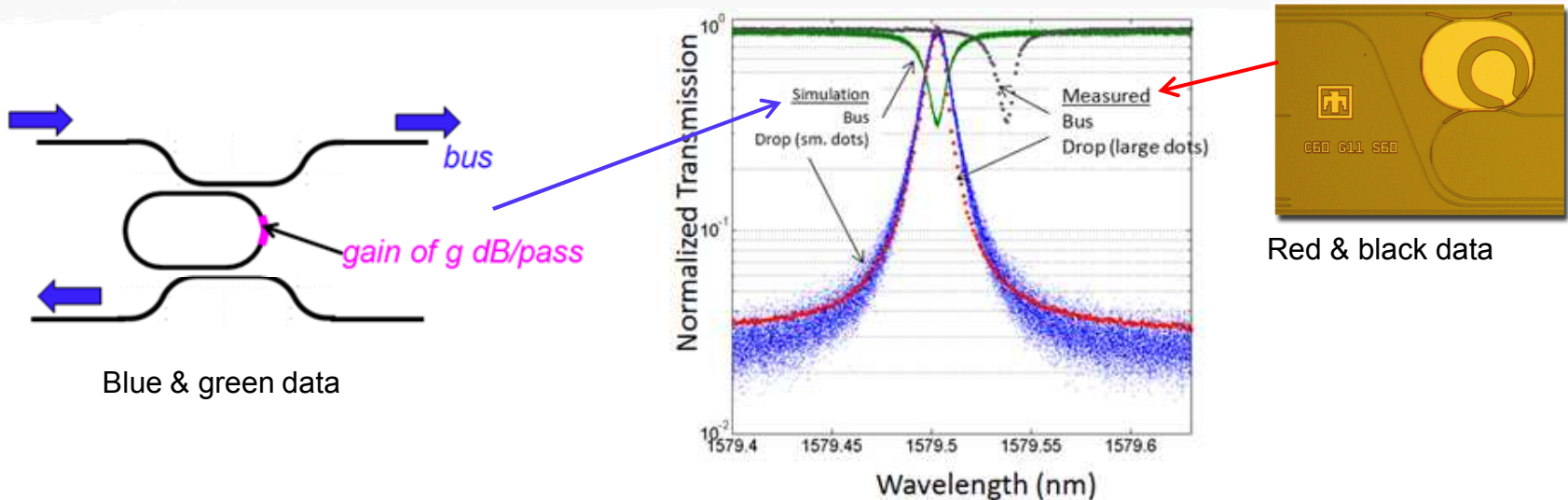
SNL Optical Channelized RF Receiver PIC

Single-chip RF-Optical Channelizer



- Analyze an RF signal for frequency content
 - Filter outputs are spectral power density integrated over the filter bandwidth
- Monolithic integration with active components such as lasers and modulators enables compact, highly functional photonic integrated circuits (PICs)
- US Patent Application
 - "Photonic Circuit", Oct. 2011
- Publications at OFC 2011
 - "Wide Dynamic Range of Ring Resonator Channel Dropping Filters with Integrated SOAs"
 - "Cascaded Double Ring Resonator Filter with Integrated SOAs"

Simulation is a Key Element of Design: Simulation Benchmark to Experiment



- Complete simulation of dynamic range and noise of active InGaAsP multi-ring filters
 - Include gain distortions and spontaneous emission noise
- Time dependent rate equation method
 - Gain and spontaneous emission modeled as function of injection current at all wavelengths simultaneously

Model of Active Ring

0.1 mW
1.54 \pm Δ μ m

Bus

Drop

Radius: 200 μ m

Couplers: 17% power cross-coupling

Passive guides: 3 cm^{-1}

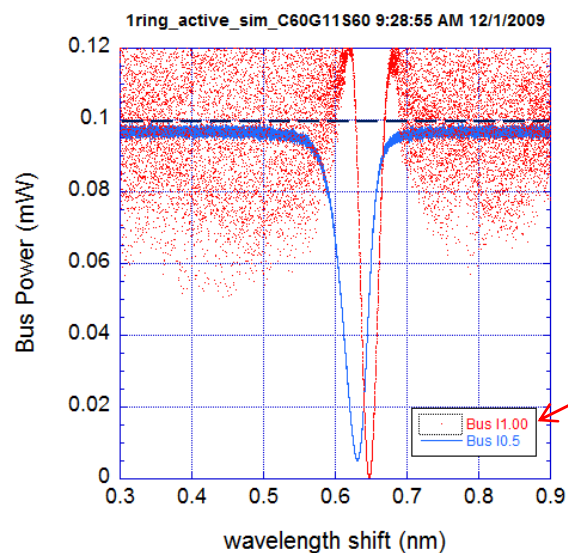
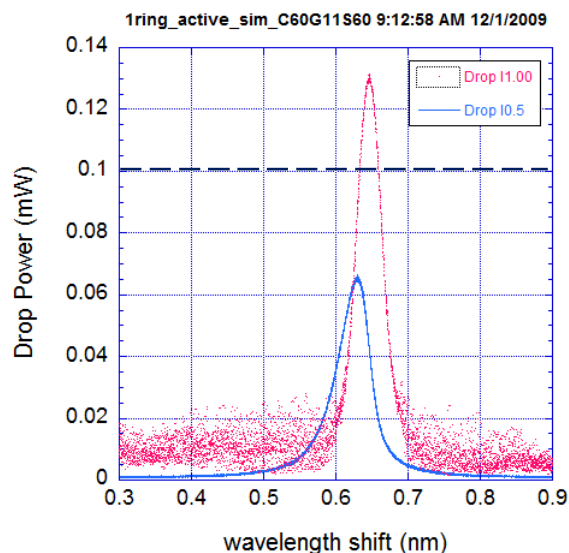
SOA: 60 μ m long

7 QW centered, 25C

1 μ m wide BH

current flow *only* in the MQW

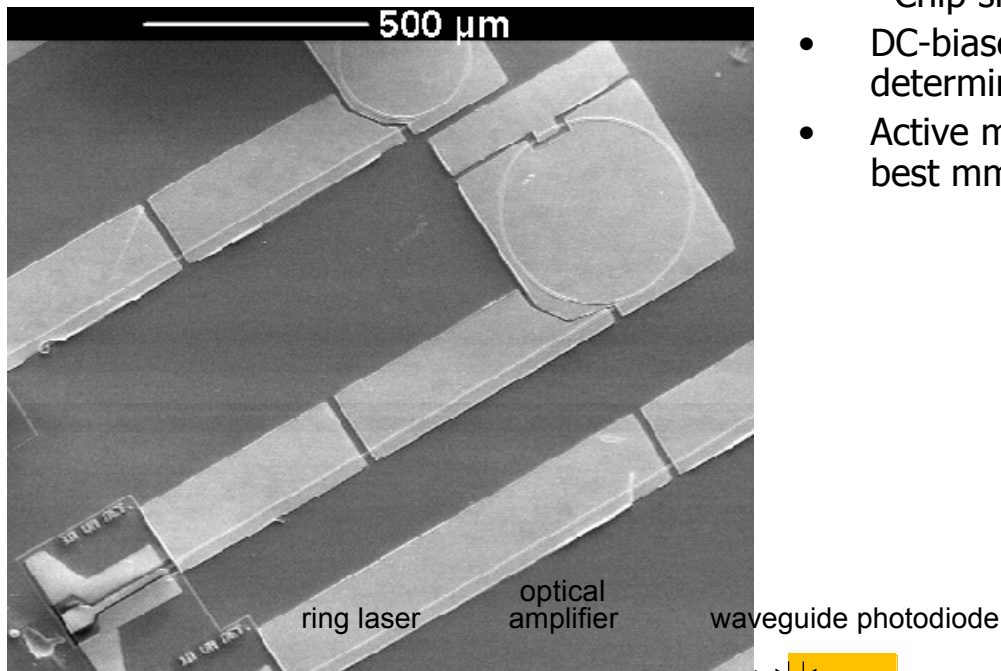
Spontaneous Coupling: 0.0037



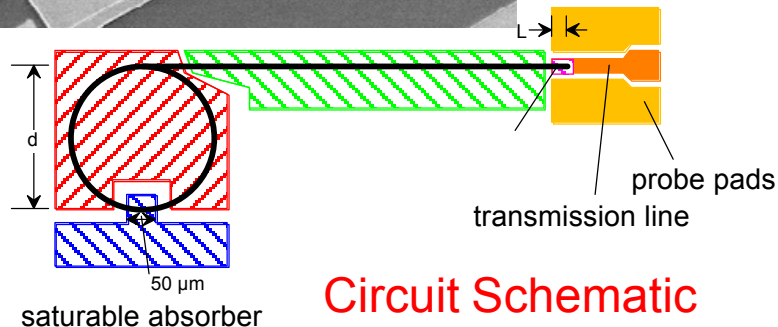
$J = 1.67 \text{ KA/cm}^2$
 $I = 1.0 \text{ mA}$

- Operation at very high gain (SOA injected current)
 - Negative insertion loss achievable, but very noisy

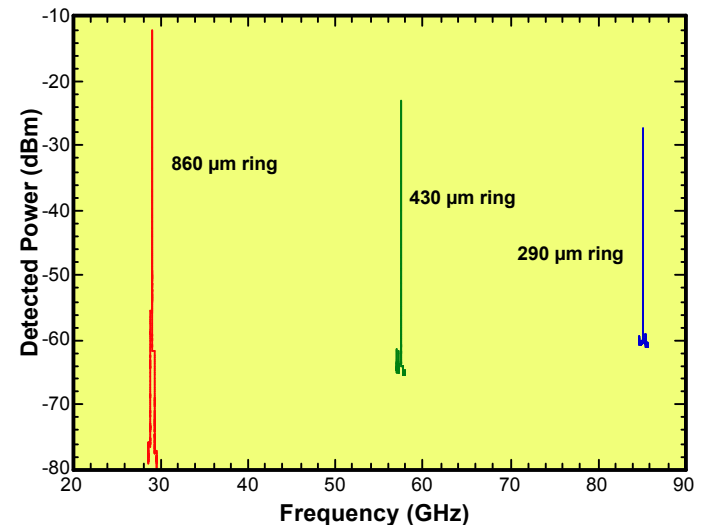
PICs for All-Optical Generation of mm-Wave Frequencies



- Monolithically integrated AlGaAs/GaAs PIC
Chip size < 2mm
- DC-biased PIC generates 30-90 GHz electrical output determined by the ring laser diameter
- Active mode-locking, singlemode rings needed for best mm-wave performance



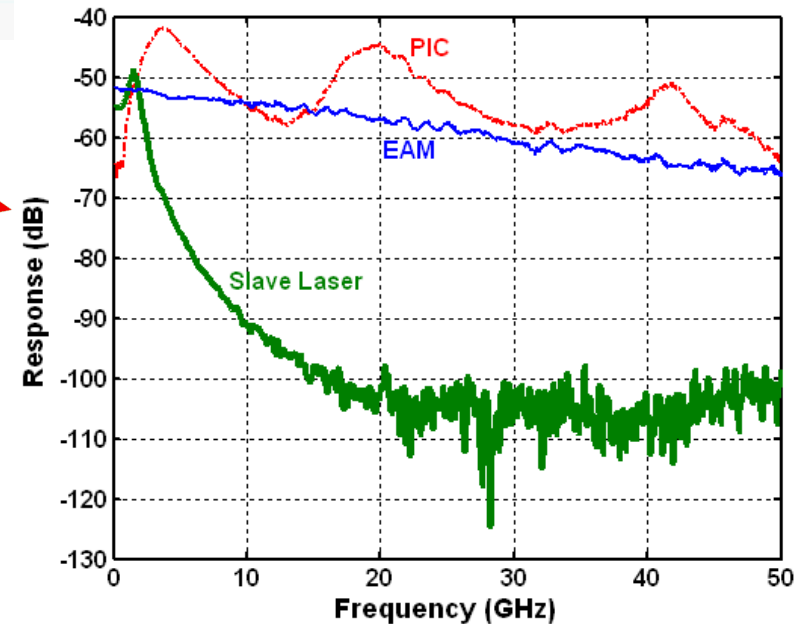
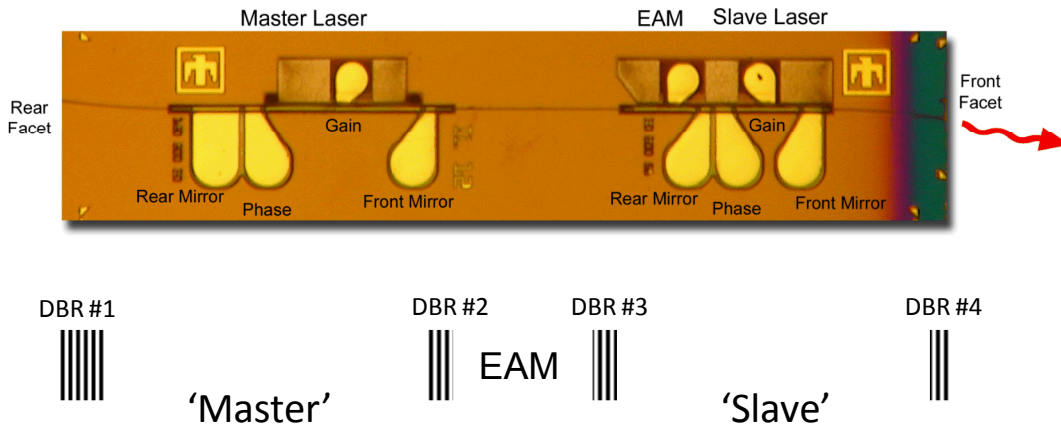
Circuit Schematic



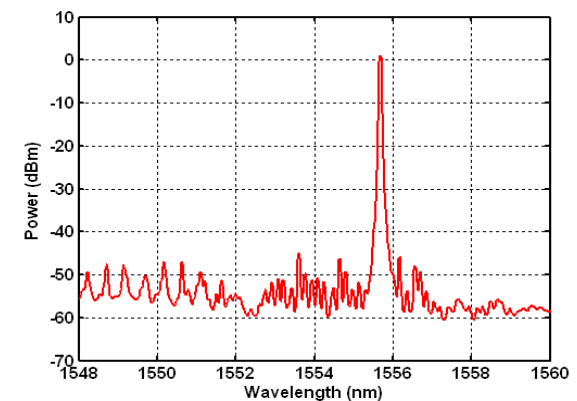
RF Spectral Output of Three Different Circuits with Different Ring Laser Diameters

BW Enhancement by On-Chip Injection Locking

RF INPUT



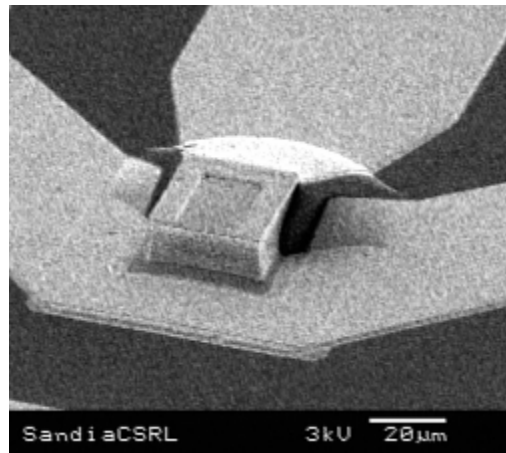
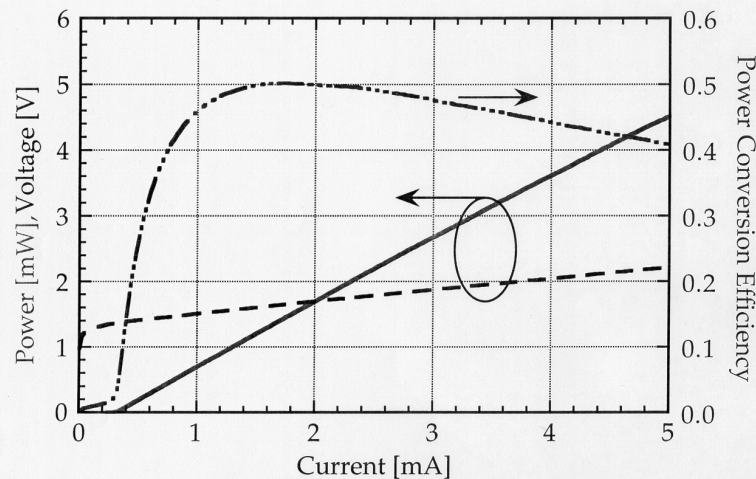
- Mutual injection locking of monolithically integrated coupled-cavity DBR lasers and EAM
 - Enhancement at difference of lasing wavelength and cavity modes of free-running lasers
 - Complex triple cavity offers many closely-spaced modes for resonance as RF tracks across frequency
- Bandwidth increased from 10 GHz to >50 GHz when operating in the mutual injection locking regime
- Increased efficiency up to 10 dB compared to laser-EAM



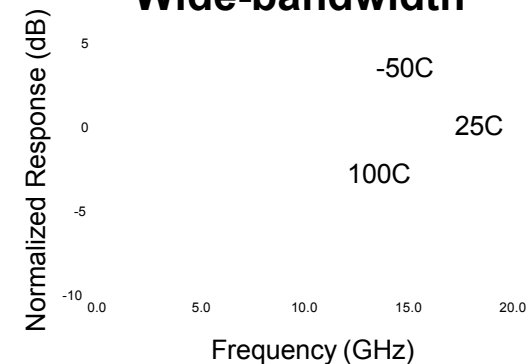
(In,Al,Ga)As/GaAs VCSELs

A radhard, efficient, low-power, wideband emitter for microsystems

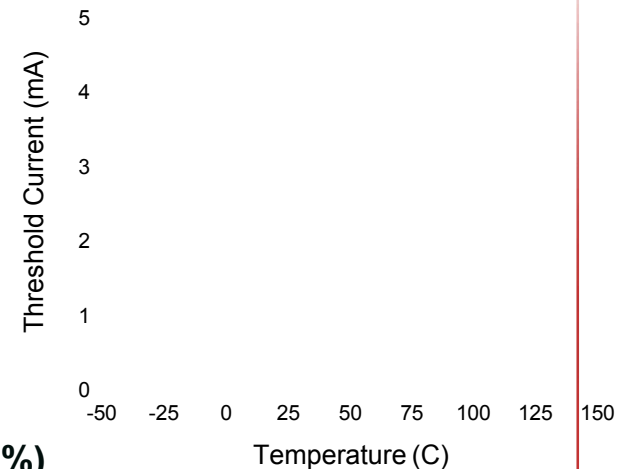
Efficient



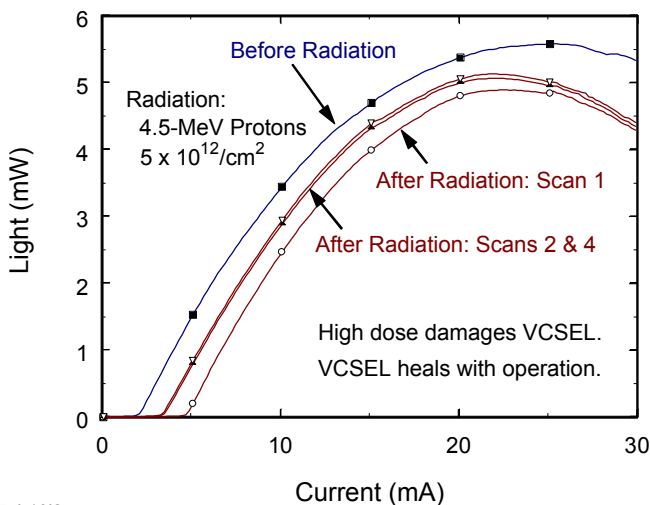
Wide-bandwidth



Thermal Stability



Radhard



VCSEL Attributes

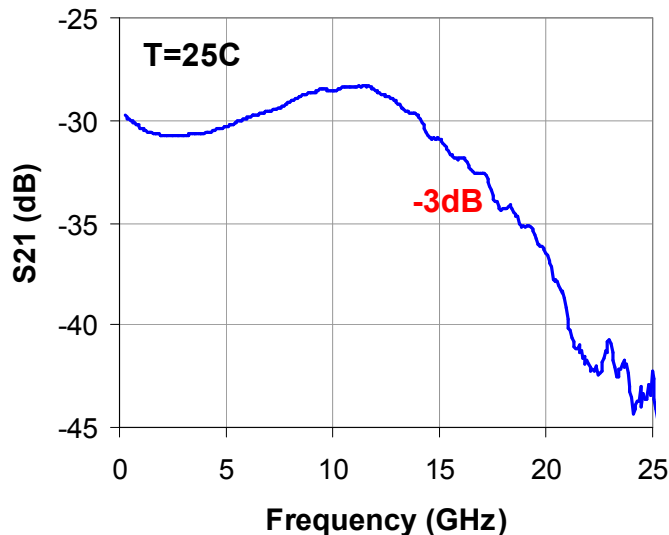
- On-wafer testing/screening
- Ease of package integration
 - surface-normal circular output
 - low beam divergence
- Small active volumes (3X8nm QWs)
- Low threshold current (<1mA)
- High efficiency operation (>30%)
- Thermal stability ($\Delta T \sim 150^\circ\text{C}$)
- High-speed (>5GHz)



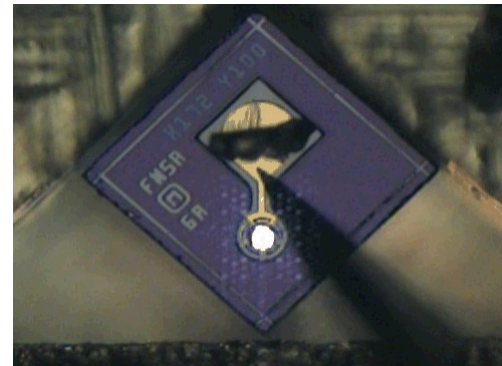
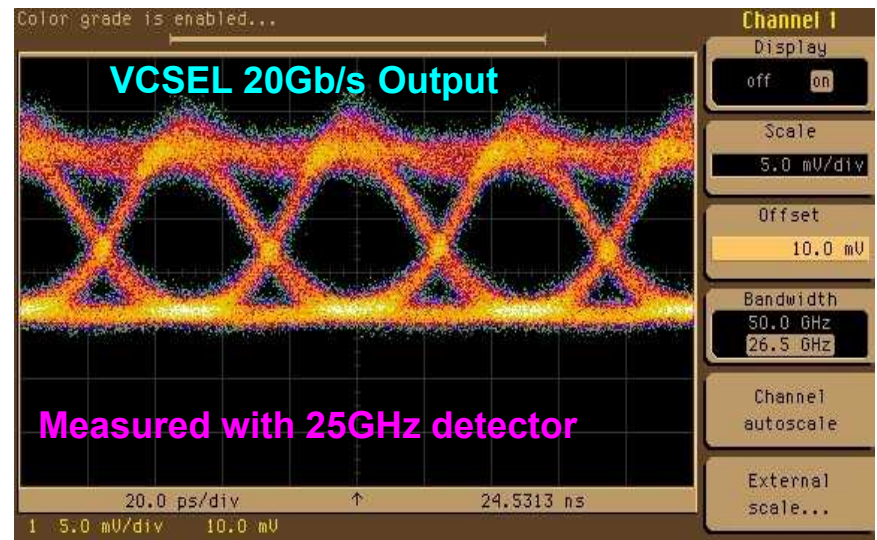
High-Speed VCSELs: 20 Gb/s at 850 nm

- Small-signal response
 - 17 GHz 3-dB frequency
 - 850-nm VCSEL compatible with datacomm standards
 - 980-nm VCSEL can achieve bandwidth > 30 GHz

S21 measurement of 850nm VCSEL



- Large-signal response



R.H. Johnson, D.K. Serkland, "17 G directly modulated datacom VCSELs", CLEO 2008.
Finisar VCSELs, tested at Sandia.

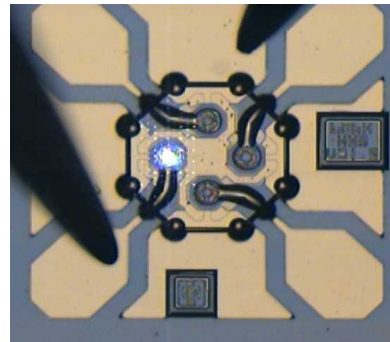


10Gb/s Low-Power VCSEL Transmitter

- Goals:
 - Threshold ≤ 0.2 mA
 - Bandwidth ≥ 8 GHz
 - Slope efficiency $\geq 50\%$
 - (photons out)/(electrons in)
 - Series resistance $\leq 100 \Omega$
 - $\Delta I = 3\text{mA} \rightarrow \Delta V = 0.3\text{V}$
- Strategy:
 - Wavelength = 980nm
 - Low threshold
 - Optimum distributed Bragg reflectors (DBRs)
 - High bandwidth
 - InGaAs quantum wells provide high differential gain
 - Power = $3\text{mW} = 1.5\text{mA} \times 2\text{V}$
 - Energy = 0.3pJ/bit

VCSEL

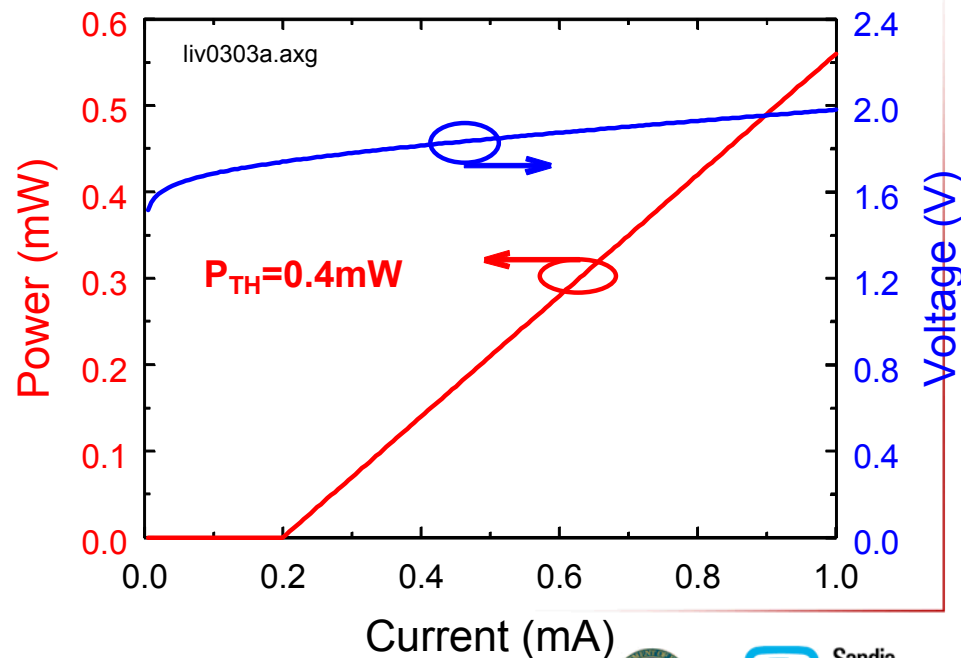
$V_B = 2.0\text{V}$



Low-voltage
CMOS
($V_{DD} = 1\text{V}$
or less)

Drive:
 $\Delta V = 0.3\text{V}$
 $\Delta I = 3\text{mA}$

Output power and Voltage drop vs. Current



Sandia
National
Laboratories